POLYMER SILVER CONDUCTOR

Low Temperature Curing

ESL 1120 is a silver-filled resin material that is designed for use as a conductor on low temperature substrates. This silver conductor may be used on flexible substrates using roller applications.

PASTE DATA

RHEOLOGY: Thixotropic, screen printable paste

VISCOSITY: 4.5±1 Pa•s
(Brookfield RVT, No. 4 Spindle, 10 rpm, 25.5±0.5°C)

SHELF LIFE: 6 months
(at 0°C recommended)

PROCESSING

DRYING AT 125°C: 1-2 minutes

CURING SCHEDULE: 150°C/30 minutes

SUBSTRATE FOR CALIBRATION: Mylar®

THINNER: ESL 1120 Thinner
TYPICAL PROPERTIES

CURED THICKNESS:
(measured on a 100mm x 10mm conductor track) 35±5µm

APPROXIMATE COVERAGE:
(at 35µm cured thickness) 35cm²/gram

RESISTIVITY:
(measured on a 100mm x 10mm conductor track) ≤20mΩ/sq.

RESISTANCE TO ACETONE:
good

FLEXIBILITY: (TO BS EN ISO 1519:1995) good, no cracking with 4mm cylindrical mandrel

ADHESION: (to DIN 53151) grade 0